

Assembly

SMT EQUIPMENT – LINE 1

- ✂ Sanyo TPM 5000 Solder Printer
- ✂ Cyberoptics SE2000 Solder volume measurement
- ✂ Sanyo TCM 3500Z High Speed chip shooter
- ✂ Sanyo TIM 5000 Flexible Placer with Flip Chip capability
- ✂ Heller 1800 Forced Convection Reflow Oven with Nitrogen Inerting



Assembly

SMT EQUIPMENT – LINE 2

- ✘ Auto Cassette Loader
- ✘ MPM UP2000 Flux Printer
- ✘ Sanyo TPM 5000 Solder Printer
- ✘ Sanyo TCM 3500Z High Speed Chip Shooter
- ✘ Sanyo TIM 5000 Flexible Placer with Flip Chip Capability
- ✘ Universal GSM Flexible Placer with Flip chip Capability
- ✘ Heller 1800 Forced Convection Reflow Oven with Nitrogen Inerting



Assembly

SMT PROCESS CAPABILITIES

- ✍ Components down to 0201
- ✍ Tape and reel, trays, waffle packs
- ✍ BGA, Micro BGA, Flip Chip, Connectors
- ✍ Flip Chip History
 - ✍ Automotive: .007" bump .020" Pitch, High temp alloy on bumps, Flux stencil printed
 - ✍ Volume: 5 Million annually since 1999
- ✍ Substrate types:
 - ✍ Ceramic (Thickfilm, Thinfilm, LTCC)
 - ✍ Organic (FR4, GeTek, Polyimide, Rogers, Flex)
 - ✍ Metal (IMS)